

HIGH-SPEED 2.5V 256/128/64K x 36 SYNCHRONOUS DUAL-PORT STATIC RAM WITH 3.3V OR 2.5V INTERFACE

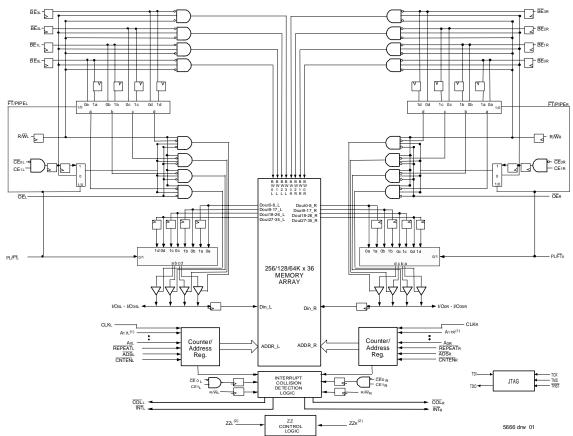
IDT70T3519/99/89S

Features:

- True Dual-Port memory cells which allow simultaneous access of the same memory location
- High-speed data access
 - Commercial: 3.4 (200MHz)/3.6ns (166MHz)/ 4.2ns (133MHz)(max.)
 - Industrial: 3.6ns (166MHz)/4.2ns (133MHz) (max.)
- Selectable Pipelined or Flow-Through output mode
- Counter enable and repeat features
- Dual chip enables allow for depth expansion without additional logic
- Full synchronous operation on both ports
 - 5ns cycle time, 200MHz operation (14Gbps bandwidth)
 - Fast 3.4ns clock to data out
 - 1.5ns setup to clock and 0.5ns hold on all control, data, and address inputs @ 200MHz
 - Data input, address, byte enable and control registers
 - Self-timed write allows fast cycle time

- Interrupt and Collision Detection Flags
- Separate byte controls for multiplexed bus and bus matching compatibility
- Dual Cycle Deselect (DCD) for Pipelined Output Mode
- 2.5V (±100mV) power supply for core
- LVTTL compatible, selectable 3.3V (±150mV) or 2.5V (±100mV) power supply for I/Os and control signals on each port
- Industrial temperature range (-40°C to +85°C) is available at 166MHz and 133MHz
- Available in a 256-pin Ball Grid Array (BGA), a 208-pin Plastic Quad Flatpack (PQFP) and 208-pin fine pitch Ball Grid Array (fpBGA)
- Supports JTAG features compliant with IEEE 1149.1
- Due to limited pin count JTAG is not supported on the 208pin PQFP package
- Green parts available, see ordering information

Functional Block Diagram



NOTES:

- 1. Address A₁₇ is a NC for the IDT70T3599. Also, Addresses A₁₇ and A₁₆ are NC's for the IDT70T3589.
- The sleep mode pin shuts off all dynamic inputs, except JTAG inputs, when asserted. All static inputs, i.e., PL/FTx and OPTx and the sleep mode pins themselves (ZZx) are not affected during sleep mode.

APRIL 2006

©2006 Integrated Device Technology, Inc.

Description:

The IDT70T3519/99/89 is a high-speed 256/128/64K x 36 bit synchronous Dual-Port RAM. The memory array utilizes Dual-Port memory cells to allow simultaneous access of any address from both ports. Registers on control, data, and address inputs provide minimal setup and hold times. The timing latitude provided by this approach allows systems to be designed with very short cycle times. With an input data register, the IDT70T3519/99/89 has been optimized for applications having unidirec-

tional or bidirectional data flow in bursts. An automatic power down feature, controlled by $\overline{\text{CE}}$ 0 and CE1, permits the on-chip circuitry of each port to enter a very low standby power mode.

The 70T3519/99/89 can support an operating voltage of either 3.3V or 2.5V on one or both ports, controllable by the OPT pins. The power supply for the core of the device (VDD) is at 2.5V.

Pin Configuration (3,4,5,6,9)

70T3519/99/89BC BC-256⁽⁷⁾

256-Pin BGA Top View⁽⁸⁾

04/10/06

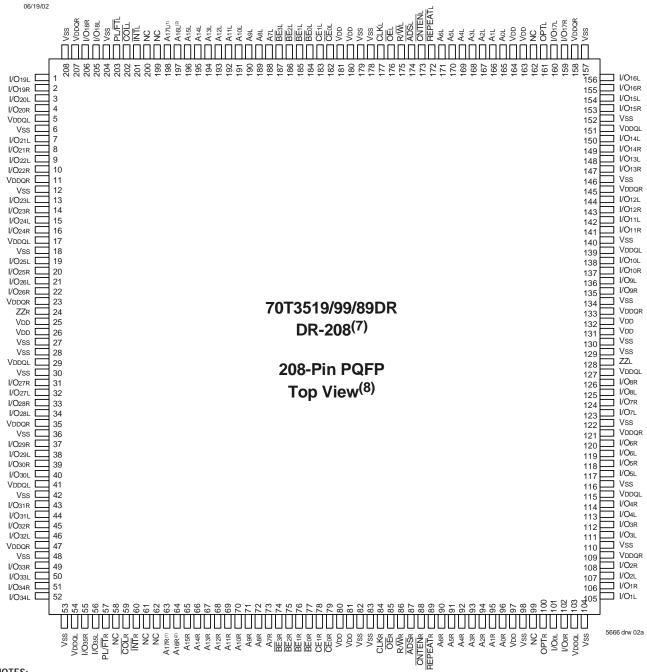
A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12	A13	A14	A15	A16
NC	TDI	NC	A17L ⁽¹⁾	A14L	A11L	A8L	BE ₂ L	CE1L	OEL	CNTENL	A 5L	A2L	A0L	NC	NC
B1	B2	B3	B4	B5	B6	B7	B8	B9	B10	B11	B12	B13	B14	B15	B16
I/O18L	NC	TDO	NC	A15L	A12L	A9L	BE3L	CE ₀ L	R/WL	REPEATL	A4L	A1L	VDD	I/O17L	NC
C1	C2	C3	C4	C5	C6	C7	C8	C9	C10	C11	C12	C13	C14	C15	C16
I/O18R	I/O19L	Vss	A16L ⁽²⁾	A13L	A10L	A7L	BE ₁ L	BE ₀ L	CLKL	ADSL	A6L	A3L	OPTL	I/O17R	I/O16L
D1	D2	D3	D4	D5	d6	d7	d8	D9	d10	d11	D12	D13	D14	D15	D16
I/O20R	I/O19R	I/ O 20L	PL/FTL	Vddq	Vddql	Vddqr	Vddqr	VDDQ	Vddql	Vddqr	Vddqr	VDD	I/O15R	I/O15L	I/O16R
E1	E2	E3	E4	E5	E6	E7	E8	E9	E10	E11	E12	E13	E14	E15	E16
I/O21R	I/O21L	I/O22L	Vddql	VDD	Vdd	INTL	Vss	Vss	Vss	VDD	VDD	Vddqr	I/O13L	I/O14L	I/O14R
F1	F2	F3	F4	F5	F6	F7	F8	F9	F10	F11	F12	F13	F14	F15	F16
I/O23L	I/ O 22R	I/ O 23R	Vddql	Vdd	NC	COLL	Vss	Vss	Vss	Vss	Vdd	Vddqr	I/O12R	I/O13R	I/O12L
G1	G2	G3	G4	G5	G6	G7	G8	G9	G10	G11	G12	G13	G14	G15	G16
I/ O 24R	I/O24L	I/O25L	Vddqr	Vss	Vss	Vss	Vss	Vss	Vss	Vss	Vss	Vddql	I/O10L	I/O11L	I/O11R
H1	H2	H3	h4	H5	H6	H7	H8	H9	H10	H11	H12	H13	H14	H15	H16
I/O26L	I/O25R	I/O26R	Vddqr	Vss	Vss	Vss	Vss	Vss	Vss	Vss	Vss	Vddq	I/O9R	IO9L	I/O10R
J1	J2	J3	J4	J5	J6	J7	J8	^{J9}	J10	J11	J12	J13	J14	J15	J16
I/O27L	I/ O 28R	I/ O 27R	Vddql	ZZR	Vss	Vss	Vss	Vss	Vss	Vss	ZZ L	Vddqr	I/O8R	I/O7R	I/O8L
K1	K2	K3	K4	K5	K6	K7	K8	K9	K10	K11	K12	K13	K14	K15	K16
I/O29R	I/ O 29L	I/O28L	Vddq	Vss	Vss	Vss	Vss	Vss	Vss	Vss	Vss	Vddqr	I/O6R	I/O6L	I/O7L
L1	L2	L3	L4	L5	L6	L7	L8	L9	L10	L11	L12	L13	L14	L15	L16
I/O30L	I/O31R	I/ O 30R	Vddqr	VDD	NC	COLR	Vss	Vss	Vss	Vss	Vdd	Vddql	I/O5L	I/O4R	I/O5R
M1	M2	M3	M4	M5	M6	M7	M8	M9	M10	M11	M12	M13	M14	M15	M16
I/O32R	I/O32L	I/O31L	Vddqr	Vdd	Vdd	INTR	Vss	Vss	Vss	Vdd	Vdd	Vddql	I/O3R	I/O3L	I/O4L
N1	N2	N3	N4	n5	N6	n7	n8	n9	N10	N11	N12	N13	N14	N15	N16
I/O33L	I/ O 34R	I/O33R	PL/FTR	Vddqr	Vddqr	Vddql	Vddql	Vddqr	Vddqr	Vddql	Vddql	Vdd	I/O2L	I/O1R	I/O2R
P1	P2	P3	P4	P5	P6	P7	P8	P9	P10	P11	P12	P13	P14	P15	P16
I/O35R	I/O34L	TMS	A 16R ⁽²⁾	A13R	A10R	A 7R	BE1R	BE0R	CLKR	ADSR	A6R	A3R	I/OoL	I/O0R	I/O1L
R1	R2	R3	R4	R5	R6	R7	R8	R9	R10	R11	R12	R13	R14	R15	R16
I/O35L	NC	TRST	NC	A15R	A12R	A 9R	BE3R	CE0R	R/WR	REPEATR	A 4R	A 1R	OPTR	NC	NC
T1	T2	T3	T4	T5	T6	T7	T8	T9	T10	T11	T12	T13	T14	T15	T16
NC	TCK	NC	A17R ⁽¹⁾	A 14R	A11R	A 8R	BE2R	CE1R	OER	CNTENR	A 5R	A 2R	A0R	NC	NC

NOTES:

- 1. Pin is a NC for IDT70T3599 and IDT70T3589.
- 2. Pin is a NC for IDT70T3589.
- 3. All VDD pins must be connected to 2.5V power supply.
- 4. All VDDQ pins must be connected to appropriate power supply: 3.3V if OPT pin for that port is set to VDD (2.5V), and 2.5V if OPT pin for that port is set to Vss (0V).
- 5. All Vss pins must be connected to ground supply.
- 6. Package body is approximately 17mm x 17mm x 1.4mm, with 1.0mm ball-pitch.
- 7. This package code is used to reference the package diagram.
- 8. This text does not indicate orientation of the actual part-marking.
- 9. Pins A15 and T15 will be VREFL and VREFR respectively for future HSTL device.

5666 drw 02d

Pin Configuration (3,4,5,6,9,10) (con't.)



NOTES:

- 1. Pin is a NC for IDT70T3599 and IDT70T3589.
- 2. Pin is a NC for IDT70T3589.
- 3. All VDD pins must be connected to 2.5V power supply.
- 4. All Vodo pins must be connected to appropriate power supply: 3.3V if OPT pin for that port is set to Vod (2.5V), and 2.5V if OPT pin for that port is set to Vss (OV).
- 5. All Vss pins must be connected to ground supply.
- 6. Package body is approximately 28mm x 28mm x 3.5mm.
- 7. This package code is used to reference the package diagram.
- 8. This text does not indicate orientation of the actual part-marking. 9. Due to limited pin count, JTAG is not supported in the DR-208 package.
- 10. Pins 162 and 99 will be VREFL and VREFR respectively for future HSTL device.

Pin Configuration (3,4,5,6,9) (con't.)

01/23/03

A1 I/O19L	A2 I/O18L	A3 Vss	A4 TDO	A5 COLL	A6 A16L ⁽²⁾	A7 A12L	A8 A8L	A9 BE1L	A10 VDD	A11 CLKL	A12 CNTENL	A13 A 4L	A14 A0L	A15 OPTL	A16 I/O17L	A17 Vss
B1 I/O20R	B2 Vss	B3 I/O18R	B4 TDI	B5 A17L ⁽¹⁾	B6 A13L	B7 A9L	B8 BE2L	B9 CE0L	B10 Vss	B11 ADSL	B12 A5L	B13 A1L	B14 NC	B15 VDDQR	B16 I/O16L	B17 I/O15R
C1 VDDQL	C2 I/O19R	C3 Vddqr	C4 PL/FTL	C5 INTL	C6 A14L	C7 A10L	C8 BE3L	C9 CE1L	C10 Vss	C11 R/WL	C12 A6L	C13 A2L	C14 VDD	C15 I/O16R	C16 I/O15L	C17 Vss
D1 I/O22L	D2 Vss	D3 I/O21L	D4 I/O20L	D5 A15L	D6 A11L	D7 A7L	D8 BEOL	D9 Vdd	D10 OEL	D11 REPEATL	D12 A3L	D13 VDD	D14 I/O17R	d15 Vddql	D16 I/O14L	D17 I/O14R
E1 I/O23L	E2 I/O22R	E3 Vddqr	E4 I/O21R										E14 I/O12L	E15 I/O13R	E16 Vss	E17 I/O13L
F1 VDDQL	F2 I/ O 23R	F3 I/O24L	F4 Vss										F14 Vss	F15 I/O12R	F16 I/O11L	F17 Vddqr
G1 I/O26L	G2 Vss	G3 I/ O 25L	G4 I/ O 24R										G14 I/O9L	G15 Vddql	G16 I/O10L	G17 I/O11R
H1 VDD	H2 I/O26R	H3 Vddqr	H4 I/O25R			70		19/99 -208		F			H14 Vdd	H15 I/O9R	H16 Vss	H17 I/O10R
J1 VDDQL	J2 Vdd	J3 Vss	J4 ZZR			9		Pin fp					J14 ZZL	J15 Vdd	J16 Vss	J17 Vddqr
K1 I/O28R	K2 Vss	K3 I/O27R	K4 Vss			2		Viev					K14 I/O7R	K15 VDDQL	K16 I/O8R	K17 Vss
L1 I/O29R	L2 I/ O 28L	l3 Vddqr	L4 I/O27L										L14 I/O6R	L15 I/O7L	L16 Vss	L17 I/O8L
M1 VDDQL	M2 I/O29L	M3 I/O30R	M4 Vss										M14 Vss	M15 I/O6L	M16 I/O5R	M17 Vddqr
N1 I/O31L	N2 Vss	N3 I/O31R	N4 I/O30L										N14 I/O3R	N15 VDDQL	N16 I/O4R	N17 I/O5L
P1 I/O32R	P2 I/O32L	p3 Vddqr	P4 I/O35R	P5 TRST	P6 A16R ⁽²⁾	P7 A12R	P8 A8R	P9 BE1R	P10 VDD	P11 CLKR	P12 CNTENR	P13 A4R	P14 I/O2L	P15 I/O3L	P16 Vss	P17 I/O4L
R1 Vss	R2 I/O33L	R3 I/O34R	R4 TCK	R5 A17R ⁽¹⁾	R6 A13R	R7 A 9R	R8 BE2R	R9 CEor	R10 Vss	R11 ADSR	R12 A 5R	R13 A 1R	R14 NC	R15 Vddql	R16 I/O1R	R17 Vddqr
T1 I/O33R	T2 I/O34L	t3 Vddql	T4 TMS	T5 INTR	T6 A14R	T7 A10R	т8 <mark>ВЕ</mark> зк	T9 CE1R	T10 Vss	T11 R/WR	T12 A 6R	T13 A2R	T14 Vss	T15 I/O0R	T16 Vss	T17 I/O2R
U1 Vss	U2 I/O35L	uз PL/FTR	U4 COLR	U5 A 15R	U6 A 11R	U7 A7R	U8 BEor	U9 Vdd	U10 OEr	U11 REPEATR		U13 A 0R	U14 VDD	U15 OPTR	U16 I/O0L	U17 I/O1L

5666 drw 02c

NOTES:

- 1. Pin is a NC for IDT70T3599 and IDT70T3589.
- 2. Pin is a NC for IDT70T3589.
- 3. All VDD pins must be connected to 2.5V power supply.
- 4. All VDDQ pins must be connected to appropriate power supply: 3.3V if OPT pin for that port is set to VDD (2.5V), and 2.5V if OPT pin for that port is set to Vss (0V).
- 5. All Vss pins must be connected to ground supply.
- 6. Package body is approximately 15mm x 15mm x 1.4mm with 0.8mm ball pitch.
- 7. This package code is used to reference the package diagram.
- 8. This text does not indicate orientation of the actual part-marking.
- 9. Pins B14 and R14 will be VREFL and VREFR respectively for future HSTL device.

Pin Names

Left Port	Right Port	Names		
CEOL, CE1L	CEOR, CE1R	Chip Enables (Input) ⁽⁷⁾		
R/\overline{W}_L	R/WR	Read/Write Enable (Input)		
ŌĒL	ŌĒR	Output Enable (Input)		
A0L - A17L ⁽⁶⁾	A0R - A17R ⁽⁶⁾	Address (Input)		
I/O0L - I/O35L	I/O0R - I/O35R	Data Input/Output		
CLKL	CLKR	Clock (Input)		
PL/FTL	PL/FT _R	Pipeline/Flow-Through (Input)		
ADSL	ADS R	Address Strobe Enable (Input)		
CNTENL	<u>CNTEN</u> R	Counter Enable (Input)		
REPEATL	REPEATR	Counter Repeat ⁽³⁾		
BEOL - BE3L	BEOR - BE3R	Byte Enables (9-bit bytes) (Input) ⁽⁷⁾		
VDDQL	VDDQR	Power (I/O Bus) (3.3V or 2.5V) ⁽¹⁾ (Input)		
OPTL	OPTR	Option for selecting VDDax ^(1,2) (Input)		
ZZL	ZZ R	Sleep Mode pin ⁽⁴⁾ (Input)		
V	DD	Power (2.5V) ⁽¹⁾ (Input)		
V	ss	Ground (0V) (Input)		
π)I ⁽⁵⁾	Test Data Input		
TD	O ⁽⁵⁾	Test Data Output		
TCK ⁽⁵⁾		Test Logic Clock (10MHz) (Input)		
TMS ⁽⁵⁾		Test Mode Select (Input)		
TRST ⁽⁵⁾		Reset (Initialize TAP Controller) (Input)		
ĪNT∟	INT r	Interrupt Flag (Output)		
COL	COLR	Collision Alert (Output)		

5666 tbl 01

MOTEC

- VDD, OPTx, and VDDQx must be set to appropriate operating levels prior to applying inputs on the I/Os and controls for that port.
- 2. OPTx selects the operating voltage levels for the I/Os and controls on that port. If OPTx is set to Vpp (2.5V), then that port's I/Os and controls will operate at 3.3V levels and Vppox must be supplied at 3.3V. If OPTx is set to Vss (0V), then that port's I/Os and address controls will operate at 2.5V levels and Vppox must be supplied at 2.5V. The OPT pins are independent of one another—both ports can operate at 3.3V levels, both can operate at 2.5V levels, or either can operate at 3.3V with the other at 2.5V.
- When REPEATx is asserted, the counter will reset to the last valid address loaded via ADSx.
- 4. The sleep mode pin shuts off all dynamic inputs, except JTAG inputs, when asserted. All static inputs, i.e., PL/FTx and OPTx and the sleep mode pins themselves (ZZx) are not affected during sleep mode. It is recommended that boundry scan not be operated during sleep mode.
- 5. Due to limited pin count, JTAG is not supported in the DR-208 package.
- Address A_{17x} is a NC for the IDT70T3599. Also, Addresses A_{17x} and A_{16x} are NC's for the IDT 70T3589.
- Chip Enables and Byte Enables are double buffered when PL/FT = ViH, i.e., the signals take two cycles to deselect.

Industrial and Commercial Temperature Ranges

Truth Table I—Read/Write and Enable Control (1,2,3,4)

ŌĒ	CLK	<u>C</u> E₀	CE ₁	BE ₃	BE ₂	BE ₁	<u>B</u> E₀	R/W	ZZ	Byte 3 I/O27-35	Byte 2 I/O ₁₈₋₂₆	Byte 1 I/O ₉₋₁₇	Byte 0 I/O ₀₋₈	MODE
Х	\uparrow	Н	Х	Х	Х	Χ	Χ	Х	L	High-Z	High-Z	High-Z	High-Z	Deselected-Power Down
Χ	\uparrow	Χ	L	Χ	Χ	Χ	Χ	Χ	L	High-Z	High-Z	High-Z	High-Z	Deselected-Power Down
Χ	\uparrow	L	Н	Н	Н	Н	Н	Χ	L	High-Z	High-Z	High-Z	High-Z	All Bytes Deselected
Χ	\uparrow	L	Н	Н	Н	Н	L	L	L	High-Z	High-Z	High-Z	DIN	Write to Byte 0 Only
Χ	\uparrow	L	Н	Н	Н	L	Н	L	L	High-Z	High-Z	DIN	High-Z	Write to Byte 1 Only
Χ	1	L	Н	Н	L	Н	Н	L	L	High-Z	DIN	High-Z	High-Z	Write to Byte 2 Only
Х	\uparrow	L	Н	L	Н	Н	Н	L	L	Din	High-Z	High-Z	High-Z	Write to Byte 3 Only
Х	\uparrow	L	Н	Н	Н	L	L	L	L	High-Z	High-Z	DIN	Din	Write to Lower 2 Bytes Only
Χ	\uparrow	L	Н	L	L	Н	Н	L	L	Din	DIN	High-Z	High-Z	Write to Upper 2 bytes Only
Х	\leftarrow	L	Н	Ш	L	L	L	L	L	Din	DIN	DIN	DIN	Write to All Bytes
L	1	L	Н	Н	Н	Н	L	Н	L	High-Z	High-Z	High-Z	Douт	Read Byte 0 Only
L	\uparrow	L	Н	Н	Н	L	Н	Н	L	High-Z	High-Z	Douт	High-Z	Read Byte 1 Only
L	\uparrow	L	Н	Н	L	Н	Н	Н	L	High-Z	Douт	High-Z	High-Z	Read Byte 2 Only
L	\uparrow	L	Н	L	Н	Н	Н	Н	L	Douт	High-Z	High-Z	High-Z	Read Byte 3 Only
L	\uparrow	L	Н	Н	Н	L	L	Н	L	High-Z	High-Z	Douт	Douт	Read Lower 2 Bytes Only
L	\uparrow	L	Н	L	L	Н	Н	Н	L	Douт	Douт	High-Z	High-Z	Read Upper 2 Bytes Only
L	\uparrow	L	Н	L	L	L	L	Н	L	Douт	Douт	Douт	Douт	Read All Bytes
Н	\uparrow	Х	Х	Х	Χ	Х	Х	Х	L	High-Z	High-Z	High-Z	High-Z	Outputs Disabled
Х	Х	Х	Х	Х	Х	Х	Х	Х	Н	High-Z	High-Z	High-Z	High-Z	Sleep Mode

NOTES: 5666 tbl 02

- 1. "H" = VIH. "L" = VIL. "X" = Don't Care.
- 2. \overline{ADS} , \overline{CNTEN} , $\overline{REPEAT} = X$.
- 3. $\overline{\text{OE}}$ and ZZ are asynchronous input signals.
- 4. It is possible to read or write any combination of bytes during a given access. A few representative samples have been illustrated here.

Truth Table II—Address Counter Control (1,2)

Address	Previous Internal Address	Internal Address Used	CLK	ĀDS	CNTEN	REPEAT ⁽⁶⁾	I/O ⁽³⁾	MODE
An	Х	An	1	L ⁽⁴⁾	Х	Н	Dvo (n)	External Address Used
Х	An	An + 1	1	Н	L ⁽⁵⁾	Н	Dvo(n+1)	Counter Enabled—Internal Address generation
Х	An + 1	An + 1	1	Н	Н	Н	Dvo(n+1)	External Address Blocked—Counter disabled (An + 1 reused)
Х	Х	An	1	Χ	Х	L ⁽⁴⁾	Di/o(n)	Counter Set to last valid ADS load

NOTES: 5666 tbl 03

- 1. "H" = V_{IH} , "L" = V_{IL} , "X" = $Don't\ Care$.
- 2. Read and write operations are controlled by the appropriate setting of R/W, CEo, CE1, BEn and OE.
- 3. Outputs configured in flow-through output mode: if outputs are in pipelined mode the data out will be delayed by one cycle.
- 4. ADS and REPEAT are independent of all other memory control signals including CEo, CE1 and BEn
- 5. The address counter advances if $\overline{\text{CNTEN}} = \text{V}_{\text{IL}}$ on the rising edge of CLK, regardless of all other memory control signals including $\overline{\text{CE}}_0$, CE₁, $\overline{\text{BE}}_n$.
- 6. When REPEAT is asserted, the counter will reset to the last valid address loaded via ADS. This value is not set at power-up: a known location should be loaded via ADS during initialization if desired. Any subsequent ADS access during operations will update the REPEAT address location.

Recommended Operating Temperature and Supply Voltage (1)

		1 2	
Grade	Ambient Temperature	GND	V DD
Commercial	0°C to +70°C	0V	2.5V <u>+</u> 100mV
Industrial	-40°C to +85°C	0V	2.5V <u>+</u> 100mV

NOTES

5666 tbl 04

1. This is the parameter TA. This is the "instant on" case temperature.

Recommended DC Operating Conditions with VDDQ at 2.5V

Symbol	Parameter	Min.	Тур.	Мах.	Unit
VDD	Core Supply Voltage	2.4	2.5	2.6	V
VDDQ	I/O Supply Voltage ⁽³⁾	2.4	2.5	2.6	V
Vss	Ground	0	0	0	V
VIН	Input High Volltage (Address, Control & Data I/O Inputs) ⁽³⁾	1.7		VDDQ + 100mV ⁽²⁾	V
VIН	Input High Voltage - JTAG	1.7		V _{DD} + 100mV ⁽²⁾	V
VIН	Input High Voltage - ZZ, OPT, PIPE/FT	VDD - 0.2V		V _{DD} + 100mV ⁽²⁾	٧
VIL	Input Low Voltage	-0.3 ⁽¹⁾	_	0.7	V
VIL	Input Low Voltage - ZZ, OPT, PIPE/FT	-0.3 ⁽¹⁾	_	0.2	٧

NOTES:

5666 tbl 05a

- 1. V_{L} (min.) = -1.0V for pulse width less than tcyc/2 or 5ns, whichever is less.
- 2. VIH (max.) = VDDQ + 1.0V for pulse width less than tcyc/2 or 5ns, whichever is less.
- 3. To select operation at 2.5V levels on the I/Os and controls of a given port, the OPT pin for that port must be set to Vss(0V), and VDDOX for that port must be supplied as indicated above.

Recommended DC Operating Conditions with Vppo at 3.3V

Symbol	Parameter	Min.	Тур.	Max.	Unit
VDD	Core Supply Voltage	2.4	2.5	2.6	٧
VDDQ	I/O Supply Voltage ⁽³⁾	3.15	3.3	3.45	V
Vss	Ground	0	0	0	V
ViH	Input High Voltage (Address, Control &Data I/O Inputs) ⁽³⁾	2.0		VDDQ + 150mV ⁽²⁾	>
ViH	Input High Voltage - JTAG	1.7		VDD + 100mV ⁽²⁾	٧
ViH	Input High Voltage - ZZ, OPT, PIPE/FT	VDD - 0.2V		VDD + 100mV ⁽²⁾	٧
VIL	Input Low Voltage	-0.3 ⁽¹⁾	_	0.8	V
VIL	Input Low Voltage - ZZ, OPT, PIPE/FT	-0.3 ⁽¹⁾		0.2	V

666 tbl 05b

NOTES:

- 1. VIL (min.) = -1.0V for pulse width less than tcyc/2, or 5ns, whichever is less.
- 2. Vih (max.) = VDDQ + 1.0V for pulse width less than tcyc/2 or 5ns, whichever is less.
- To select operation at 3.3V levels on the I/Os and controls of a given port, the OPT pin
 for that port must be set to VDD (2.5V), and VDDOX for that port must be supplied as indicated
 above.

8

Absolute Maximum Ratings (1)

Symbol	Rating	Commercial & Industrial	Unit
VTERM (VDD)	VDD Terminal Voltage with Respect to GND	-0.5 to 3.6	V
Vterm ⁽²⁾ (Vddq)	VDDQ Terminal Voltage with Respect to GND	-0.3 to VDDQ + 0.3	V
V _{TERM} (2) (INPUTS and I/O's)	Input and I/O Terminal Voltage with Respect to GND	-0.3 to VDDQ + 0.3	V
TBIAS ⁽³⁾	Temperature Under Bias	-55 to +125	°C
Тѕтс	Storage Temperature	-65 to +150	°C
NLT	Junction Temperature	+150	°C
IOUT(For VDDQ = 3.3V)	DC Output Current	50	mA
IOUT(For VDDQ = 2.5V)	DC Output Current	40	mA

NOTES:

666 tbl 06

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause
 permanent damage to the device. This is a stress rating only and functional operation of the
 device at these or any other conditions above those indicated in the operational sections
 of this specification is not implied. Exposure to absolute maximum rating conditions for
 extended periods may affect reliability.
- This is a steady-state DC parameter that applies after the power supply has reached its nominal operating value. Power sequencing is not necessary; however, the voltage on any Input or I/O pin cannot exceed VDDQ during power supply ramp up.
- 3. Ambient Temperature under DC Bias. No AC Conditions. Chip Deselected.

Capacitance (1)

(TA = +25°C, F = 1.0MHz) PQFP ONLY

Symbol	Parameter	Conditions ⁽²⁾	Max.	Unit
CIN	Input Capacitance	VIN = 3dV	8	pF
Соит ⁽³⁾	Output Capacitance	Vout = 3dV	10.5	pF

NOTES

5666 tbl 07

- These parameters are determined by device characterization, but are not production tested.
- 3dV references the interpolated capacitance when the input and output switch from 0V to 3V or from 3V to 0V.
- 3. Cout also references CI/o.

DC Electrical Characteristics Over the Operating

Temperature and Supply Voltage Range (VDD = 2.5V ± 100mV)

			70T3519)/99/89S	
Symbol	Parameter	Test Conditions	Min.	Max.	Unit
ILI	Input Leakage Current ⁽¹⁾	VDDQ = Max., VIN = 0V to VDDQ	_	10	μΑ
Iu	JTAG & ZZ Input Leakage Current ^(1,2)	VDD = Max., VIN = OV to VDD	_	± 30	μΑ
ILO	Output Leakage Current ^(1,3)	$\overline{CE}_0 = VIH \text{ or } CE_1 = VIL, VOUT = 0V \text{ to } VDDQ$	_	10	μA
Vol (3.3V)	Output Low Voltage ⁽¹⁾	IOL = +4mA, VDDQ = Min.	_	0.4	V
Vон (3.3V)	Output High Voltage ⁽¹⁾	IOH = -4mA, VDDQ = Min.	2.4	_	V
Vol (2.5V)	Output Low Voltage ⁽¹⁾	IOL = +2mA, VDDQ = Min.	_	0.4	V
Vон (2.5V)	Output High Voltage ⁽¹⁾	IOH = -2mA, VDDQ = Min.	2.0	_	V

NOTES

5666 tbl 08

- 1. VDDQ is selectable (3.3V/2.5V) via OPT pins. Refer to p.5 for details.
- 2. Applicable only for TMS, TDI and TRST inputs.
- 3. Outputs tested in tri-state mode.

DC Electrical Characteristics Over the Operating

			'(0)	0
Temperature	and Suppl	v Voltage Range	$\Xi^{(3)}$ (VDD	= 2.5V + 100mV

					S2	9/99/89 200 Only ⁽⁸⁾	S1 Co	9/99/89 166 m'l nd ⁽⁷⁾	S1 Co	9/99/89 133 m'l Ind	
Symbol	Parameter	Test Condition	Versio	n	Typ. ⁽⁴⁾	Max.	Typ. ⁽⁴⁾	Max.	Typ. ⁽⁴⁾	Max.	Unit
IDD	Dynamic Operating Current (Both	CEL and CER= VIL, Outputs Disabled,	COM'L	S	375	525	320	450	260	370	mA
	Ports Active)	$f = fMAX^{(1)}$	IND	S	_	_	320	510	260	450	
ISB1 ⁽⁶⁾	Standby Current (Both Ports - TTL	$\overline{CE}L = \overline{CE}R = VIH$ $f = fMAX^{(1)}$	COM'L	S	205	270	175	230	140	190	mA
	Level Inputs)	I = IMAX*/	IND	S	_	_	175	275	140	235	IIIA
ISB2 ⁽⁶⁾	Standby Current (One Port - TTL	CE"A" = VIL and CE"B" = VIH ⁽⁵⁾	COM'L	S	300	375	250	325	200	250	mA
	Level Inputs)	Active Port Outputs Disabled, f=fMAX ⁽¹⁾	IND	S	-	-	250	365	200	310	IIIA
ISB3	Full Standby Current (Both Ports - CMOS	Both Ports $\overline{CE}L$ and $\overline{CE}R \ge VDDQ - 0.2V$, $VIN \ge VDDQ - 0.2V$	COM'L	S	5	15	5	15	5	15	mA
	Level Inputs)	or VIN $\leq 0.2V$, $f = 0^{(2)}$	IND	S	_	_	5	20	5	20	IIIA
ISB4 ⁽⁶⁾	Full Standby Current (One Port - CMOS	$\overline{CE}^{"}A" \leq 0.2V$ and $\overline{CE}^{"}B" \geq VDDQ - 0.2V^{(5)}$	COM'L	S	300	375	250	325	200	250	mA
	(One Port - CMOS $VIN \ge VDDQ - 0.2V$ or $VIN \le 0.2V$ Level Inputs) Active Port, Outputs Disabled, $f = fMAX^{(1)}$		IND	S	_	_	250	365	200	310	IIIA
lzz	Sleep Mode Current (Both Ports - TTL	ZZL = ZZR = VIH f=fMAX ⁽¹⁾		S	5	15	5	15	5	15	mΛ
	Level Inputs)	I-IWAA	IND	S	_	_	5	20	5	20	mA

5666 tbl 09

- 1. At f = fmax, address and control lines (except Output Enable) are cycling at the maximum frequency clock cycle of 1/tcvc, using "AC TEST CONDITIONS".
- 2. f = 0 means no address, clock, or control lines change. Applies only to input at CMOS level standby.
- 3. Port "A" may be either left or right port. Port "B" is the opposite from port "A".
- 4. VDD = 2.5V, TA = 25°C for Typ, and are not production tested. IDD DC(f=0) = 15mA (Typ).
- 5. $\overline{CE}x = VIL \text{ means } \overline{CE}ox = VIL \text{ and } CE1x = VIH$
 - $\overline{CE}x = VIH \text{ means } \overline{CE}0x = VIH \text{ or } CE1x = VIL$

 - $\begin{array}{l} \overline{\text{CE}} x \leq 0.2 \text{V means } \overline{\text{CE}} ox \leq 0.2 \text{V and } C\text{E1}x \geq \text{VDD} 0.2 \text{V} \\ \overline{\text{CE}} x \geq \text{VDD} 0.2 \text{V means } \overline{\text{CE}} ox \geq \text{VDD} 0.2 \text{V or } C\text{E1}x 0.2 \text{V} \\ \end{array}$
 - "X" represents "L" for left port or "R" for right port.
- 6. ISB1, ISB2 and ISB4 will all reach full standby levels (ISB3) on the appropriate port(s) if ZZL and/or ZZR = VIH.
- 7. 166MHz I-Temp is not available in the BF-208 package.
- 8. 200Mhz is not available in the BF-208 and DR-208 packages.

AC Test Conditions (VDDQ - 3.3V/2.5V)

7.6 1631 0011d1t10113 (VDbg - 3.3 V/2.3 V)						
Input Pulse Levels (Address & Controls)	GND to 3.0V/GND to 2.4V					
Input Pulse Levels (I/Os)	GND to 3.0V/GND to 2.4V					
Input Rise/Fall Times	2ns					
Input Timing Reference Levels	1.5V/1.25V					
Output Reference Levels	1.5V/1.25V					
Output Load	Figure 1					

5666 tbl 10

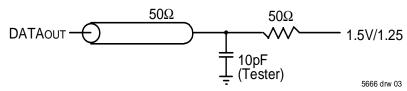
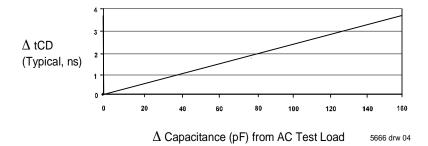


Figure 1. AC Output Test load.



AC Electrical Characteristics Over the Operating Temperature Range (Read and Write Cycle Timing) $^{(2,3)}$ (VDD = 2.5V ± 100mV, TA = 0°C to +70°C)

	and write cycle rinning) (VDD = 2.3	70T35	19/99/89 200 Only ⁽⁵⁾	l s	19/99/89 166 om'l nd ⁽⁴⁾	S ^r Co	9/99/89 133 om'l Ind	
Symbol	Parameter	Min.	Max.	Min.	Max	Min.	Мах.	Unit
tcyc1	Clock Cycle Time (Flow-Through) ⁽¹⁾	15		20		25		ns
tcyc2	Clock Cycle Time (Pipelined) ⁽¹⁾	5		6		7.5	-	ns
tcH1	Clock High Time (Flow-Through) ⁽¹⁾	6		8	—	10		ns
tcL1	Clock Low Time (Flow-Through) ⁽¹⁾	6		8		10		ns
tcH2	Clock High Time (Pipelined) ⁽²⁾	2		2.4		3		ns
tCL2	Clock Low Time (Pipelined) ⁽¹⁾	2	_	2.4	_	3	_	ns
tsa	Address Setup Time	1.5		1.7	_	1.8	_	ns
tha	Address Hold Time	0.5	_	0.5	_	0.5	_	ns
tsc	Chip Enable Setup Time	1.5		1.7		1.8		ns
thc	Chip Enable Hold Time	0.5	_	0.5		0.5		ns
tsB	Byte Enable Setup Time	1.5	_	1.7	_	1.8	-	ns
tнв	Byte Enable Hold Time	0.5		0.5		0.5	_	ns
tsw	R/W Setup Time	1.5	_	1.7	_	1.8		ns
tHW	R/W Hold Time	0.5	_	0.5	_	0.5		ns
tsp	Input Data Setup Time	1.5	_	1.7	_	1.8	_	ns
tho	Input Data Hold Time	0.5	_	0.5	_	0.5	_	ns
tsad	ADS Setup Time	1.5	_	1.7		1.8		ns
thad	ADS Hold Time	0.5	_	0.5	_	0.5	_	ns
tscn	CNTEN Setup Time	1.5	_	1.7		1.8		ns
thcn	CNTEN Hold Time	0.5	_	0.5		0.5		ns
tsrpt	REPEAT Setup Time	1.5	_	1.7		1.8	_	ns
thrpt	REPEAT Hold Time	0.5	_	0.5		0.5	_	ns
toe	Output Enable to Data Valid	_	4.4		4.4	_	4.6	ns
tolz ⁽⁶⁾	Output Enable to Output Low-Z	1	_	1	_	1		ns
tohz ⁽⁶⁾	Output Enable to Output High-Z	1	3.4	1	3.6	1	4.2	ns
tcD1	Clock to Data Valid (Flow-Through) ⁽¹⁾	_	10		12	_	15	ns
tCD2	Clock to Data Valid (Pipelined) ⁽¹⁾	_	3.4		3.6	_	4.2	ns
toc	Data Output Hold After Clock High	1	_	1	_	1		ns
tckhz ⁽⁶⁾	Clock High to Output High-Z	1	3.4	1	3.6	1	4.2	ns
tcklz ⁽⁶⁾	Clock High to Output Low-Z	1	_	1	_	1	_	ns
tins	Interrupt Flag Set Time	_	7	_	7	_	7	ns
tinr	Interrupt Flag Reset Time	_	7		7	_	7	ns
tcols	Collision Flag Set Time	_	3.4		3.6	_	4.2	ns
tcolr	Collision Flag Reset Time	_	3.4		3.6	_	4.2	ns
tzzsc	Sleep Mode Set Cycles	2		2	_	2		cycles
tzzrc	Sleep Mode Recovery Cycles	3	_	3	_	3		cycles
Port-to-Port D	, , ,		<u> </u>		I	L -	I	1 .,
tco	Clock-to-Clock Offset	4	_	5		6	_	ns
tors	Clock-to-Clock Offset for Collision Detection	+	efer to Coll		tion Timin		Page 21	
	THE THE SECOND COMMISSION DESCRIPTION	5030 1	10 0011			g .a.ə.ic 01	490 21	

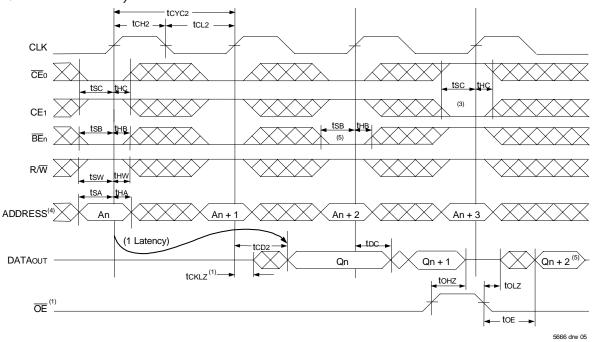
NOTES:

5666 tbl 11

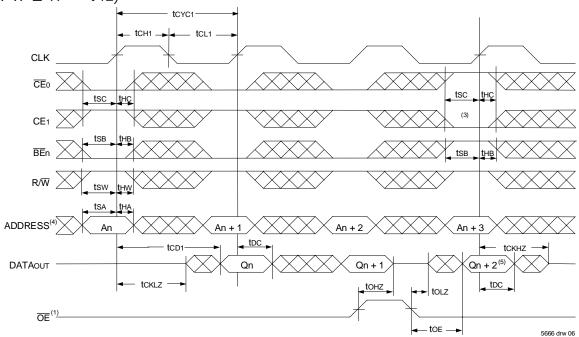
- 1. The Pipelined output parameters (tcyc2, tcp2) apply to either or both left and right ports when PL/FTx = Vpp (2.5V). Flow-through parameters (tcyc1, tcp1) apply when PL/FT = Vss (0V) for that port.
- 2. All input signals are synchronous with respect to the clock except for the asynchronous Output Enable (OE), PL/FT and OPT. PL/FT and OPT should be treated as DC signals, i.e. steady state during operation.
- 3. These values are valid for either level of VDDO (3.3V/2.5V). See page 6 for details on selecting the desired operating voltage levels for each port.
- 4. 166MHz I-Temp is not available in the BF-208 package.
- 5. 200Mhz is not available in the BF-208 and DR-208 packages.
- 6. Guaranteed by design (not production tested).

12

Timing Waveform of Read Cycle for Pipelined Operation (**FT**/PIPE'x' = VIH)^(1,2)



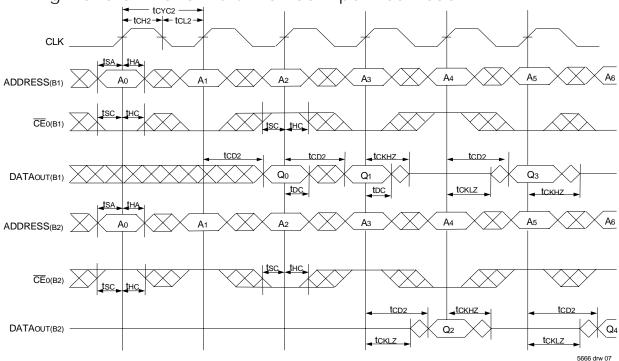
Timing Waveform of Read Cycle for Flow-through Output $(\mathbf{FT}/PIPE"x" = VIL)^{(1,2,6)}$



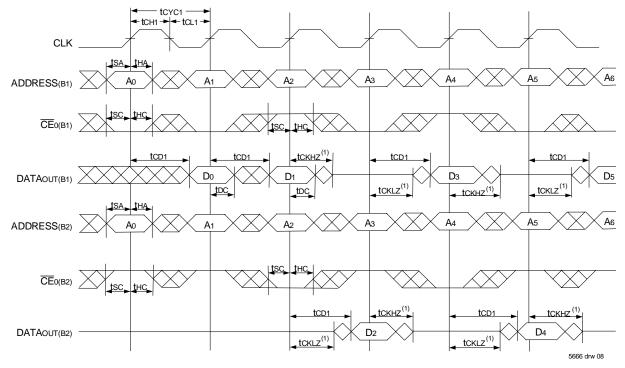
NOTES:

- 1. $\overline{\text{OE}}$ is asynchronously controlled; all other inputs depicted in the above waveforms are synchronous to the rising clock edge.
- 2. $\overline{ADS} = VIL$, \overline{CNTEN} and $\overline{REPEAT} = VIH$.
- The output is disabled (High-Impedance state) by \(\overline{CE}_0 = V_{IH}, CE_1 = V_{IL}, \(\overline{BE}_n = V_{IH} \) following the next rising edge of the clock. Refer to Truth Table 1.
- 4. Addresses do not have to be accessed sequentially since $\overline{ADS} = VIL$ constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. If \overline{BE}_n was HIGH, then the appropriate Byte of DATAout for Qn + 2 would be disabled (High-Impedance state).
- 6. "x" denotes Left or Right port. The diagram is with respect to that port.

Timing Waveform of a Multi-Device Pipelined Read (1,2)



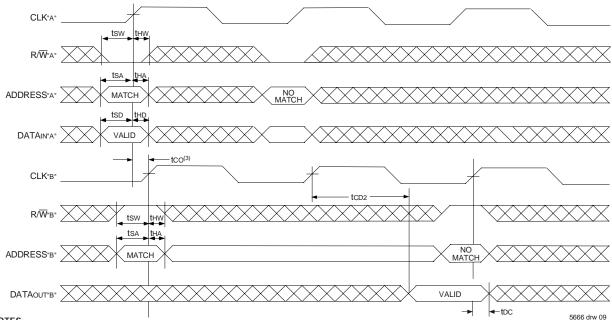
Timing Waveform of a Multi-Device Flow-Through Read (1,2)



NOTES:

- B1 Represents Device #1; B2 Represents Device #2. Each Device consists of one IDT70T3519/99/89 for this waveform, and are setup for depth expansion in this example. ADDRESS(B1) = ADDRESS(B2) in this situation.
- 2. \overline{BE}_{n} , \overline{OE} , and \overline{ADS} = VIL; $\overline{CE1(B1)}$, $\overline{CE1(B2)}$, $\overline{R/W}$, \overline{CNTEN} , and \overline{REPEAT} = VIH.

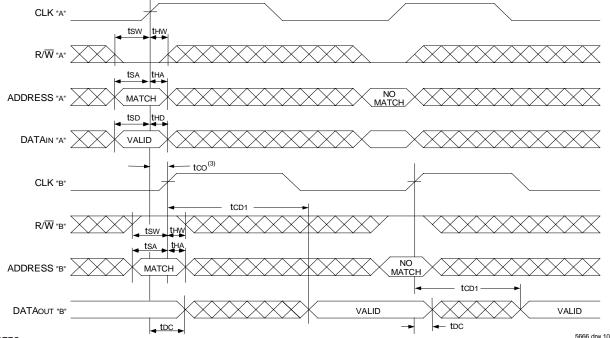
Timing Waveform of Left Port Write to Pipelined Right Port Read (1,2,4)



NOTES:

- 1. \overline{CE}_0 , \overline{BE}_n , and $\overline{ADS} = VIL$; CE_1 , \overline{CNTEN} , and $\overline{REPEAT} = VIH$.
- 2. \overline{OE} = V_{IL} for Port "B", which is being read from. \overline{OE} = V_{IH} for Port "A", which is being written to.
- 3. If tco ≤ minimum specified, then data from Port "B" read is not valid until following Port "B" clock cycle (ie, time from write to valid read on opposite port will be tco + 2 tcvc2 + tcp2). If tco > minimum, then data from Port "B" read is available on first Port "B" clock cycle (ie, time from write to valid read on opposite port will be tco + tcvc2 + tcp2).
- 4. All timing is the same for Left and Right ports. Port "A" may be either Left or Right port. Port "B" is the opposite of Port "A"

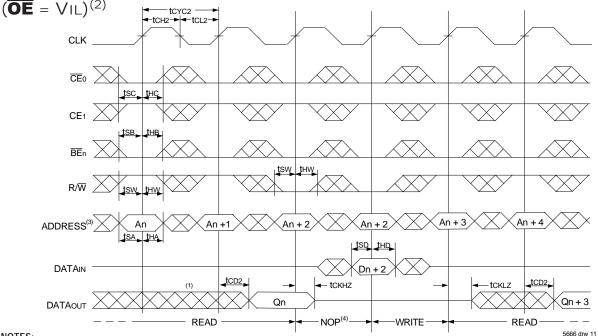
Timing Waveform with Port-to-Port Flow-Through Read (1,2,4)



NOTES

- 1. $\overline{CE_0}$, \overline{BE} n, and \overline{ADS} = VIL; CE1, \overline{CNTEN} , and \overline{REPEAT} = VIH.
- 2. \overline{OE} = V_{IL} for the Right Port, which is being read from. \overline{OE} = V_{IH} for the Left Port, which is being written to.
- 3. If tco ≤ minimum specified, then data from Port "B" read is not valid until following Port "B" clock cycle (i.e., time from write to valid read on opposite port will be tco + tcyc + tcp1). If tco > minimum, then data from Port "B" read is available on first Port "B" clock cycle (i.e., time from write to valid read on opposite port will be tco + tcp1).
- 4. All timing is the same for both left and right ports. Port "A" may be either left or right port. Port "B" is the opposite of Port "A".

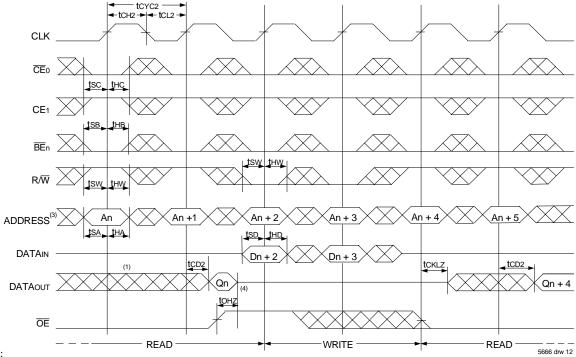
Timing Waveform of Pipelined Read-to-Write-to-Read



NOTES:

- 1. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
 2. $\overline{\text{CEo}}$, $\overline{\text{BE}}_{\text{N}}$, and $\overline{\text{ADS}}$ = V_{IL}; CE1, $\overline{\text{CNTEN}}$, and $\overline{\text{REPEAT}}$ = V_{IH}. "NOP" is "No Operation".
- Addresses do not have to be accessed sequentially since ADS = Vil. constantly loads the address on the rising edge of the CLK; numbers
- 4. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be re-written to guarantee data integrity.

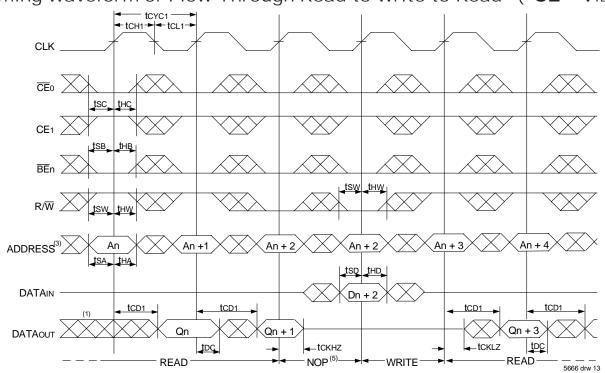
Timing Waveform of Pipelined Read-to-Write-to-Read (Teach Controlled) (2)



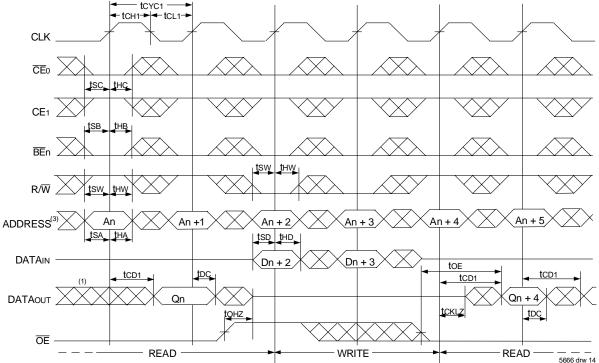
NOTES:

- Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- CEO, BEn, and ADS = VIL; CE1, CNTEN, and REPEAT = VIH.
- Addresses do not have to be accessed sequentially since ADS = Vil. constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 4. This timing does not meet requirements for fastest speed grade. This waveform indicates how logically it could be done if timing so allows.

Timing Waveform of Flow-Through Read-to-Write-to-Read (**OE** = VIL)(2)



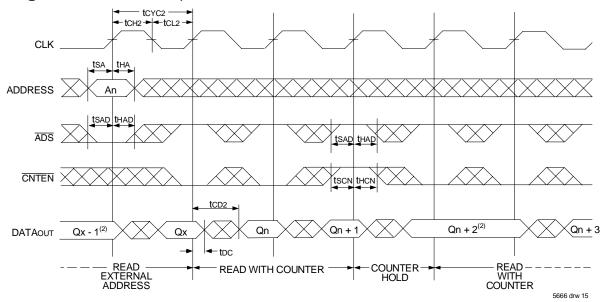
Timing Waveform of Flow-Through Read-to-Write-to-Read (**OE** Controlled)⁽²⁾



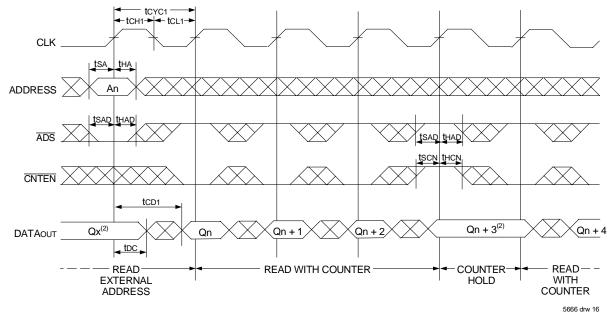
NOTES

- 1. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 2. $\overline{\text{CE}}_0$, $\overline{\text{BE}}_n$, and $\overline{\text{ADS}} = \text{Vil.}$; $\overline{\text{CE}}_1$, $\overline{\text{CNTEN}}$, and $\overline{\text{REPEAT}} = \text{Vil.}$
- Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 4. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be re-written to guarantee data integrity.

Timing Waveform of Pipelined Read with Address Counter Advance (1)



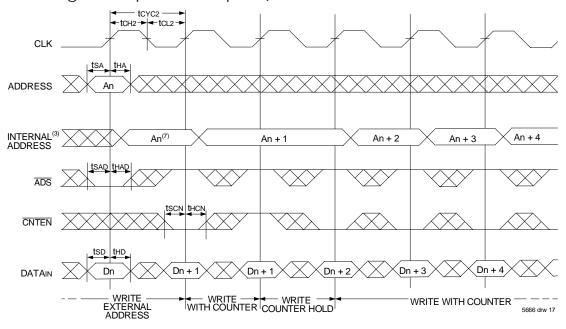
Timing Waveform of Flow-Through Read with Address Counter Advance (1)



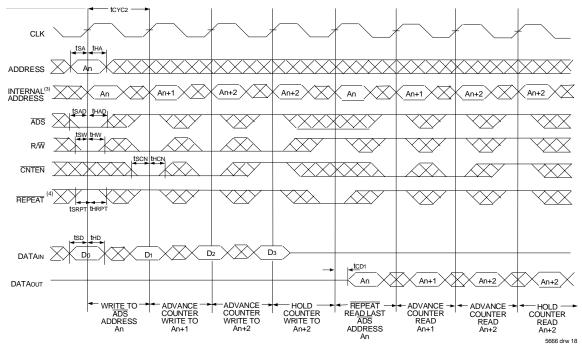
NOTES

- 1. \overline{CE}_0 , \overline{OE} , $\overline{BE}_1 = V_{IL}$; CE_1 , R/\overline{W} , and $\overline{REPEAT} = V_{IH}$.
- 2. If there is no address change via $\overline{ADS} = VIL$ (loading a new address) or $\overline{CNTEN} = VIL$ (advancing the address), i.e. $\overline{ADS} = VIH$ and $\overline{CNTEN} = VIH$, then the data output remains constant for subsequent clocks.

Timing Waveform of Write with Address Counter Advance (Flow-through or Pipelined Inputs) (1)



Timing Waveform of Counter Repeat (2,6)

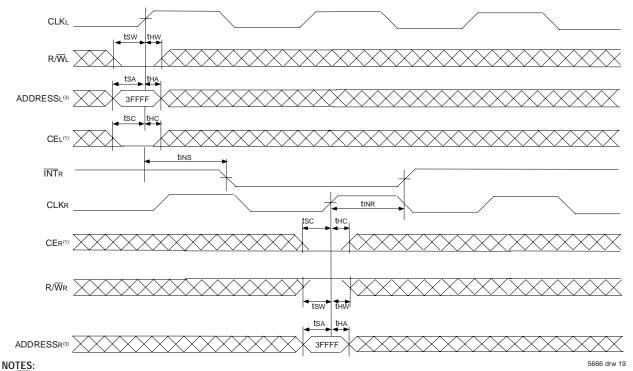


NOTES:

- 1. $\overline{CE_0}$, $\overline{BE_n}$, and $R/\overline{W} = V_{IL}$; CE_1 and $\overline{REPEAT} = V_{IH}$.
- 2. \overline{CE}_0 , $\overline{BE}_n = VIL$; $CE_1 = VIH$.
- 3. The "Internal Address" is equal to the "External Address" when $\overline{ADS} = V_{IL}$ and equals the counter output when $\overline{ADS} = V_{IH}$.

 4. No dead cycle exists during \overline{REPEAT} operation. A \overline{READ} or WRITE cycle may be coincidental with the counter \overline{REPEAT} cycle: Address loaded by last valid ADS load will be accessed. For more information on REPEAT function refer to Truth Table II.
- CNTEN = VIL advances Internal Address from 'An' to 'An +1'. The transition shown indicates the time required for the counter to advance. The 'An +1'Address is written to during this cycle.
- 6. For Pipelined Mode user should add 1 cycle latency for outputs as per timing waveform of read cycle for pipelined operations.

Waveform of Interrupt Timing (2)



1. \overline{CE}_0 = VIL and CE1 = VIH

2. All timing is the same for Left and Right ports.

3. Address is for internal register, not the external bus, i.e., address needs to be qualified by one of the Address counter control signals.

Truth Table III — Interrupt Flag (1)

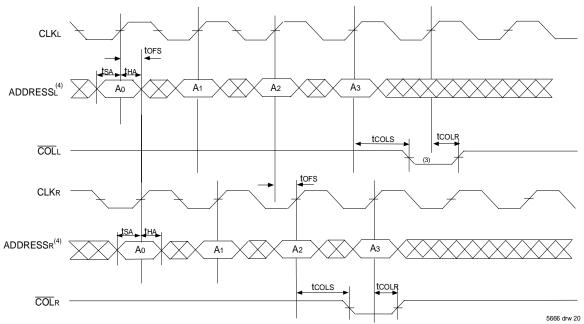
		Left Port	Left Port Right Port							
CLKL	$R/\overline{W}L^{(2)}$	CEL ⁽²⁾	A17L-A0L ^(3,4,5)	ΪΝΤι	CLKR	R/W̄R ⁽²⁾	CER ⁽²⁾	A 17R- A 0R ^(3,4,5)	ĪN₹R	Function
1	L	L	3FFFF	Х	↑	Х	Х	Х	L	Set Right INTR Flag
\uparrow	Х	Х	Х	Х	1	Н	L	3FFFF	Н	Reset Right INTR Flag
1	Х	Х	Х	L	↑	L	L	3FFFE	Х	Set Left INTL Flag
↑	Н	L	3FFFE	Н	1	Х	Х	X	Х	Reset Left INTL Flag

NOTES

5666 tbl 12

- 1. $\overline{\text{INT}}_{\text{L}}$ and $\overline{\text{INT}}_{\text{R}}$ must be initialized at power-up by Resetting the flags.
- 2. $\overline{\text{CE}}_0 = \text{VIL}$ and $\text{CE}_1 = \text{VIH}$. $\text{R}\overline{\text{W}}$ and CE are synchronous with respect to the clock and need valid set-up and hold times.
- 3. A17x is a NC for IDT70T3599, therefore Interrupt Addresses are 1FFFF and 1FFFE.
- 4. A17x and A16x are NC's for IDT70T3589, therefore Interrupt Addresses are FFFF and FFFE.
- 5. Address is for internal register, not the external bus, i.e., address needs to be qualified by one of the Address counter control signals.

Waveform of Collision Timing(1,2) Both Ports Writing with Left Port Clock Leading



- NOTES: 1. $\overline{CE}_0 = V_{IL}$, $CE_1 = V_{IH}$.
- 2. For reading port, $\overline{\text{OE}}$ is a Don't care on the Collision Detection Logic. Please refer to Truth Table IV for specific cases.
- 3. Leading Port Output flag might output 3tcyc2 + tcoLs after Address match.
- 4. Address is for internal register, not the external bus, i.e., address needs to be qualified by one of the Address counter control signals.

Collision Detection Timina(3,4)

Cycle Time	tors (ns)				
Cycle Time	Region 1 (ns) (1)	Region 2 (ns) (2)			
5ns	0 - 2.8	2.81 - 4.6			
6ns	0 - 3.8	3.81 - 5.6			
7.5ns	0 - 5.3	5.31 - 7.1			

5666 tbl 13

NOTES:

- 1. Region 1
 - Both ports show collision after 2nd cycle for Addresses 0, 2, 4 etc.
- Leading port shows collision after 3rd cycle for addresses 0, 3, 6, etc. while trailing port shows collision after 2nd cycle for addresses 0, 2, 4 etc.
- 3. All the production units are tested to midpoint of each region.
- 4. These ranges are based on characterization of a typical device.

Truth Table IV — Collision Detection Flag

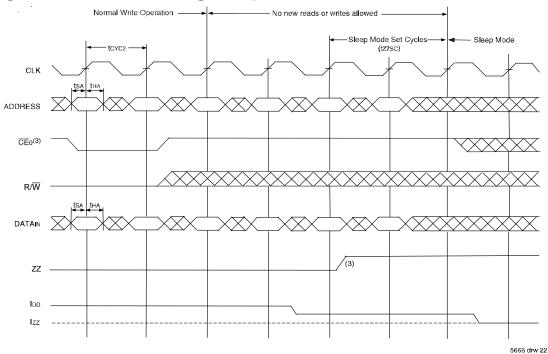
Left Port										
CLKL	R/WL ⁽¹⁾	CEL ⁽¹⁾	A17L-A0L ⁽²⁾	COLL	CLKR	R/W̄ _R ⁽¹⁾	CER ⁽¹⁾	A 17R -A 0R ⁽²⁾	COLR	Function
1	Н	L	MATCH	Н	↑	Н	L	MATCH	Н	Both ports reading. Not a valid collision. No flag output on either port.
1	Н	L	MATCH	L	↑	L	L	MATCH	Н	Left port reading, Right port writing. Valid collision, flag output on Left port.
1	L	L	MATCH	Н	↑	Н	L	MATCH	L	Right port reading, Left port writing. Valid collision, flag output on Right port.
1	L	L	MATCH	L	↑	L	L	MATCH	L	Both ports writing. Valid collision. Flag output on both ports.

NOTES:

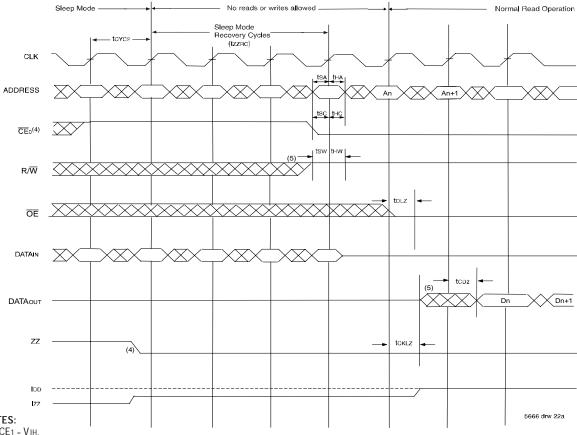
5666 tbl 14

- 1. $\overline{\text{CE}}_0$ = VIL and CE1 = VIH. R/ $\overline{\text{W}}$ and CE are synchronous with respect to the clock and need valid set-up and hold times.
- 2. Address is for internal register, not the external bus, i.e., address needs to be qualified by one of the Address counter control signals.

Timing Waveform - Entering Sleep Mode (1,2)



Timing Waveform - Exiting Sleep Mode (1,2)



NOTES:

- 2. All timing is same for Left and Right ports. 3. CEo has to be deactivated (CEo = ViH) three cycles prior to asserting ZZ (ZZx = ViH) and held for two cycles after asserting ZZ (ZZx = ViH).
- 4. CEo has to be deactivated (CEo = VIH) one cycle prior to de-asserting ZZ (ZZx = VIL) and held for three cycles after de-asserting ZZ (ZZx = VIL).
- 5. The device must be in Read Mode (R/W High) when exiting sleep mode. Outputs are active but data is not valid until the following cycle.

Functional Description

The IDT70T3519/99/89 provides a true synchronous Dual-Port Static RAM interface. Registered inputs provide minimal set-up and hold times on address, data, and all critical control inputs. All internal registers are clocked on the rising edge of the clock signal, however, the self-timed internal write pulse width is independent of the cycle time.

An asynchronous output enable is provided to ease asynchronous bus interfacing. Counter enable inputs are also provided to stall the operation of the address counters for fast interleaved memory applications.

A HIGH on $\overline{\text{CE}}$ oor a LOW on CE1 for one clock cycle will power down the internal circuitry to reduce static power consumption. Multiple chip enables allow easier banking of multiple IDT70T3519/99/89s for depth expansion configurations. Two cycles are required with $\overline{\text{CE}}$ 0 LOW and CE1 HIGH to re-activate the outputs.

Interrupts

If the user chooses the interrupt function, a memory location (mail box or message center) is assigned to each port. The left port interrupt flag (INTL) is asserted when the right port writes to memory location 3FFFE (HEX), where a write is defined as $\overline{CE}R = R/\overline{W}R = VIL$ per the Truth Table. The left port clears the interrupt through access of address location 3FFFE when $\overline{CE}L = VIL$ and $R/\overline{W}L = VIH$. Likewise, the right port interrupt flag (\overline{INTR}) is asserted when the left port writes to memory location 3FFFF (HEX) and to clear the interrupt flag (INTR), the right port must read the memory location 3FFFF (1FFFF or 1FFFE for IDT70T3599 and FFFF or FFFE for IDT70T3589). The message (36 bits) at 3FFFE or 3FFFF (1FFFF or 1FFFE for IDT70T3599 and FFFF or FFFE for IDT70T3589) is user-defined since it is an addressable SRAM location. If the interrupt function is not used, address locations 3FFFE and 3FFFF (1FFFF or 1FFFE for IDT70T3599 and FFFF or FFFE for IDT70T3589) are not used as mail boxes, but as part of the random access memory. Refer to Truth Table III for the interrupt operation.

Collision Detection

Collision is defined as an overlap in access between the two ports resulting in the potential for either reading or writing incorrect data to a specific address. For the specific cases: (a) Both ports reading - no data is corrupted, lost, or incorrectly output, so no collision flag is output on either port. (b) One port writing, the other port reading - the end result of the write will still be valid. However, the reading port might capture data that is in a state of transition and hence the reading port's collision flag is output. (c) Both ports writing - there is a risk that the two ports will interfere with each other, and the data stored in memory will not be a valid write from either port (it may essentially be a random combination of the two). Therefore, the collision flag is output on both ports. Please refer to Truth Table IV for all of the above cases.

The alert flag (COL_x) is asserted on the 2nd or 3rd rising clock edge of the affected port following the collision, and remains low for one cycle. Please refer to Collision Detection Timing table on Page 21. During that next cycle, the internal arbitration is engaged in resetting the alert flag (this avoids a specific requirement on the part of the user to reset the alert flag). If two collisions occur on subsequent clock cycles, the second collision may not generate the appropriate alert

flag. A third collision will generate the alert flag as appropriate. In the event that a user initiates a burst access on both ports with the same starting address on both ports and one or both ports writing during each access (i.e., imposes a long string of collisions on contiguous clock cycles), the alert flag will be asserted and cleared every other cycle. Please refer to the Collision Detection timing waveform on Page 21Collision detection on the IDT70T3519/99/89 represents a significant advance in functionality over current sync multi-ports, which have no such capability. In addition to this functionality the IDT70T3519/99/89 sustains the key features of bandwidth and flexibility. The collision detection function is very useful in the case of bursting data, or a string of accesses made to sequential addresses, in that it indicates a problem within the burst, giving the user the option of either repeating the burst or continuing to watch the alert flag to see whether the number of collisions increases above an acceptable threshold value. Offering this function on chip also allows users to reduce their need for arbitration circuits, typically done in CPLD's or FPGA's. This reduces board space and design complexity, and gives the user more flexibility in developing a solution.

Sleep Mode

The IDT70T3519/99/89 is equipped with an optional sleep or low power mode on both ports. The sleep mode pin on both ports is asynchronous and active high. During normal operation, the ZZ pin is pulled low. When ZZ is pulled high, the port will enter sleep mode where it will meet lowest possible power conditions. The sleep mode timing diagram shows the modes of operation: Normal Operation, No Read/Write Allowed and Sleep Mode.

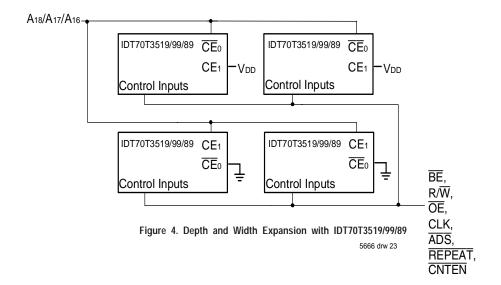
For normal operation all inputs must meet setup and hold times prior to sleep and after recovering from sleep. Clocks must also meet cycle high and low times during these periods. Three cycles prior to asserting ZZ (ZZx = VIH) and three cycles after de-asserting ZZ (ZZx = VIL), the device must be disabled via the chip enable pins. If a write or read operation occurs during these periods, the memory array may be corrupted. Validity of data out from the RAM cannot be guaranteed immediately after ZZ is asserted (prior to being in sleep). When exiting sleep mode, the device must be in Read mode (R/ \overline{W} x = VIH) when chip enable is asserted, and the chip enable must be valid for one full cycle before a read will result in the output of valid data.

During sleep mode the RAM automatically deselects itself. The RAM disconnects its internal clock buffer. The external clock may continue to run without impacting the RAMs sleep current (lzz). All outputs will remain in high-Z state while in sleep mode. All inputs are allowed to toggle. The RAM will not be selected and will not perform any reads or writes.

Depth and Width Expansion

The IDT70T3519/99/89 features dual chip enables (refer to Truth Table I) in order to facilitate rapid and simple depth expansion with no requirements for external logic. Figure 4 illustrates how to control the various chip enables in order to expand two devices in depth.

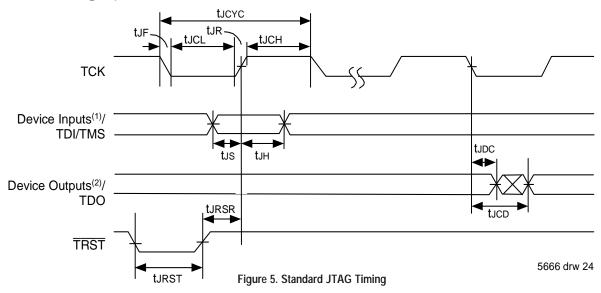
The IDT70T3519/99/89 can also be used in applications requiring expanded width, as indicated in Figure 4. Through combining the control signals, the devices can be grouped as necessary to accommodate applications needing 72-bits or wider.



NOTE:

1. A₁₈ is for IDT70T3519, A₁₇ is for IDT70T3599, A₁₆ is for IDT70T3589.

JTAG Timing Specifications



NOTES:

- 1. Device inputs = All device inputs except TDI, TMS, and TRST.
- 2. Device outputs = All device outputs except TDO.

JTAG AC Electrical Characteristics (1,2,3,4)

		70	T3519/99/	89
Symbol	Parameter	Min.	Max.	Units
tucyc	JTAG Clock Input Period	100	_	ns
исн	JTAG Clock HIGH	40		ns
ticl	JTAG Clock Low	40	_	ns
tur	JTAG Clock Rise Time	_	3 ⁽¹⁾	ns
₩F	JTAG Clock Fall Time	_	3 ⁽¹⁾	ns
URST	JTAG Reset	50	_	ns
URSR	JTAG Reset Recovery	50	_	ns
ticd	JTAG Data Output	_	25	ns
tido	JTAG Data Output Hold	0	_	ns
tus	JTAG Setup	15	_	ns
tıн	JTAG Hold	15	_	ns

NOTES:

5666 tbl 15

- 1. Guaranteed by design.
- 2. 30pF loading on external output signals.
- 3. Refer to AC Electrical Test Conditions stated earlier in this document.
- 4. JTAG operations occur at one speed (10MHz). The base device may run at any speed specified in this datasheet.

Identification Register Definitions

Instruction Field	Value	Description
Revision Number (31:28)	0x0	Reserved for version number
IDT Device ID (27:12)	0x330 ⁽¹⁾	Defines IDT part number
IDT JEDEC ID (11:1)	0x33	Allows unique identification of device vendor as IDT
ID Register Indicator Bit (Bit 0)	1	Indicates the presence of an ID register

NOTE:

5666 tbl 16

Scan Register Sizes

Register Name	Bit Size
Instruction (IR)	4
Bypass (BYR)	1
Identification (IDR)	32
Boundary Scan (BSR)	Note (3)

5666 tbl 17

System Interface Parameters

Instruction	Code	Description
EXTEST	0000	Forces contents of the boundary scan cells onto the device outputs ⁽¹⁾ . Places the boundary scan register (BSR) between TDI and TDO.
BYPASS	1111	Places the bypass register (BYR) between TDI and TDO.
IDCODE	0010	Loads the ID register (IDR) with the vendor ID code and places the register between TDI and TDO.
HIGHZ	0100	Places the bypass register (BYR) between TDI and TDO. Forces all device output drivers to a High-Z state except $\overline{\text{COL}}x$ & $\overline{\text{INT}}x$ outputs.
CLAMP	0011	Uses BYR. Forces contents of the boundary scan cells onto the device outputs. Places the bypass register (BYR) between TDI and TDO.
SAMPLE/PRELOAD	0001	Places the boundary scan register (BSR) between TDI and TDO. SAMPLE allows data from device inputs (2) to be captured in the boundary scan cells and shifted serially through TDO. PRELOAD allows data to be input serially into the boundary scan cells via the TDI.
RESERVED	0101, 0111, 1000, 1001, 1010, 1011, 1100	Several combinations are reserved. Do not use codes other than those identified above.
PRIVATE	0110,1110,1101	For internal use only.

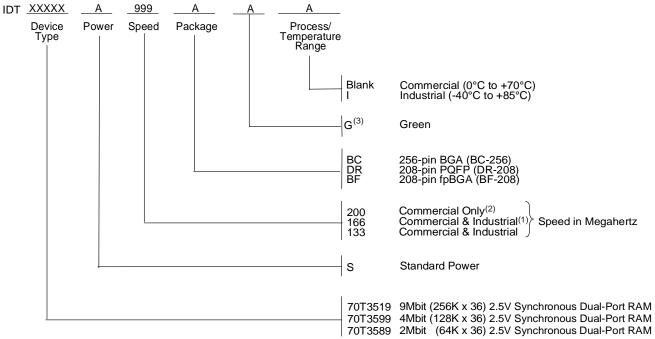
5666 tbl 18

NOTES:

- 1. Device outputs = All device outputs except TDO.
- 2. Device inputs = All device inputs except TDI, TMS, and $\overline{\text{TRST}}$.
- 3. The Boundary Scan Descriptive Language (BSDL) file for this device is available on the IDT website (www.idt.com), or by contacting your local IDT sales representative.

^{1.} Device ID for IDT70T3599 is 0x331. Device ID for IDT70T3589 is 0x332.

Ordering Information



NOTES:

5666 drw 25

- 1. 166MHz I-Temp is only available in the BC-256 package.
- 2. 200Mhz is only available in the BC-256 package.
- 3. Green parts available. For specific speeds, packages and powers contact your local sales office.

IDT Clock Solution for IDT70T3519/99/89 Dual-Port

	Dual-Port I/O	Specitications		Clock Specif	IDT	IDT			
IDT Dual-Port Part Number	Voltage	I/O Input Capacitano		Input Duty Cycle Requirement	Maximum Frequency	Jitter Tolerance	PLL Clock Device	Non-PLL Clock Device	
70T3519/99/89	2.5	LVTTL	8pF	40%	200	75ps	5T2010	5T9010 5T905, 5T9050 5T907, 5T9070	

5666 tbl 19

Datasheet Document History:

01/23/03:		Initial Datasheet
01/30/03:	Page 1	Corrected 208-pin package from TQFP to PQFP
04/25/03:	Page 11	Added Capacitance Derating drawing
	Page 12	Changed tins and ting specs in AC Electrical Characteristics table
11/11/03:	Page 10	Updated power numbers in DC Electrical Characteristics table
	Page 12	Added to Fs symbol and parameter to AC Electrical Characteristics table
	Page 21	Updated Collision Timing waveform
	Page 22	Added Collision Detection Timing table and footnotes
	Page 26	Updated HIGHZ function in System Interface Parameters table
	Page 27	Added IDT Clock Solution table
03/30/04:	Page 22 & 23	Clarified Sleep Mode Text and Waveforms
	Page 1 & 27	Removed Preliminary status
04/22/04:	Page 6	Added another sentence to footnote 4 to recommend that boundary scan not be operated during sleep mode
04/12/05:	Page 27	Clarified footnotes 1 & 2 for the ordering information
	Page 1 & 28	Replaced old IDT тм with new IDT тм logo
	Page 1	Added green availability to features
	Page 27	Added green indicator to ordering information
02/07/06:	Page 7	Changed footnote 2 for Truth Table I from ADS, CNTEN, REPEAT = V _{IH} to ADS, CNTEN, REPEAT = X
04/10/06:	Page 1,3 & 12	Changed FTx/PLx to PLx/FTx on diagrams and Notes.



CORPORATE HEADQUARTERS
6024 Silver Creek Valley Road
San Jose, CA 95138

for SALES: 800-345-7015 or 408-284-8200 fax: 408-284-2775 www.idt.com

for Tech Support: 408-284-2794 DualPortHelp@idt.com

The IDT logo is a registered trademark of Integrated Device Technology, Inc.